Switch-mode Power Rectifiers

DPAK Surface Mount Package

These state-of-the-art devices are designed for use as output rectifiers, free wheeling, protection and steering diodes in switching power supplies, inverters and other inductive switching circuits.

Features

- Extremely Fast Switching
- Extremely Low Forward Drop
- Platinum Barrier with Avalanche Guardrings
- NRVBD and SBRD Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes; 260°C Max. for 10 Seconds
- ESD Ratings:
 - ◆ Machine Model = C
 - ♦ Human Body Model = 3B



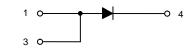
ON Semiconductor®

www.onsemi.com

SCHOTTKY BARRIER RECTIFIERS 3.0 AMPERES, 20 – 60 VOLTS



DPAK CASE 369C



MARKING DIAGRAM



Y = Year
WW = Work Week
B3x0 = Device Code
x = 2, 3, 4, 5, or 6
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	MBRD/SBRD8					
		320	330	340	350	360	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	V
Average Rectified Forward Current (T _C = +125°C, Rated V _R)	I _{F(AV)}	3			Α		
Peak Repetitive Forward Current, T _C = +125°C (Rated V _R , Square Wave, 20 kHz)	I _{FRM}	6			Α		
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	75			Α		
Peak Repetitive Reverse Surge Current (2 μs, 1 kHz)	I _{RRM}	1		Α			
Operating Junction Temperature Range (Note 1)	TJ	−65 to +175			°C		
Storage Temperature Range	T _{stg}	-65 to +175		°C			
Voltage Rate of Change (Rated V _R)	dv/dt	10,000			V/μs		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	6	°C/W
Maximum Thermal Resistance, Junction-to-Ambient (Note 2)		80	°C/W

^{2.} Rating applies when surface mounted on the minimum pad size recommended.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) $i_F = 3$ Amps, $T_C = +25^{\circ}C$ $i_F = 3$ Amps, $T_C = +125^{\circ}C$ $i_F = 6$ Amps, $T_C = +25^{\circ}C$ $i_F = 6$ Amps, $T_C = +125^{\circ}C$	V _F	0.6 0.45 0.7 0.625	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, T _C = +25°C) (Rated dc Voltage, T _C = +125°C)	i _R	0.2 20	mA

^{3.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

ORDERING INFORMATION

Device	Package	Shipping [†]			
MBRD320G		75 Units / Rail			
SBRD8320G*		75 Units / Rail			
MBRD320RLG		1,800 Tape & Reel			
MBRD320T4G		2,500 Tape & Reel			
SBRD8320T4G*		2,500 Tape & Reel			
MBRD330G		75 Units / Rail			
SBRD8330G*		75 Units / Rail			
MBRD330RLG		1,800 Tape & Reel			
MBRD330T4G		2,500 Tape & Reel			
SBRD8330T4G*		2,500 Tape & Reel			
MBRD340G		75 Units / Rail			
SBRD8340G*		75 Units / Rail			
MBRD340RLG	1	1,800 Tape & Reel			
MBRD340T4G	DPAK	2,500 Tape & Reel			
SBRD8340T4G*	(Pb-Free)	2,500 Tape & Reel			
MBRD350G		75 Units / Rail 75 Units / Rail			
SBRD8350G*					
MBRD350RLG		1,800 Tape & Reel			
SBRD8350RLG*		1,800 Tape & Reel			
MBRD350T4G		2,500 Tape & Reel			
SBRD8350T4G*		2,500 Tape & Reel			
MBRD360G		75 Units / Rail			
SBRD8360G*		75 Units / Rail			
MBRD360RLG		1,800 Tape & Reel			
SBRD8360RLG*		1,800 Tape & Reel			
MBRD360T4G		2,500 Tape & Reel			
NRVBD360VT4G*	1	2,500 Tape & Reel			
SBRD8360T4G*	7	2,500 Tape & Reel			

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NRVBD and SBRD Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

TYPICAL CHARACTERISTICS

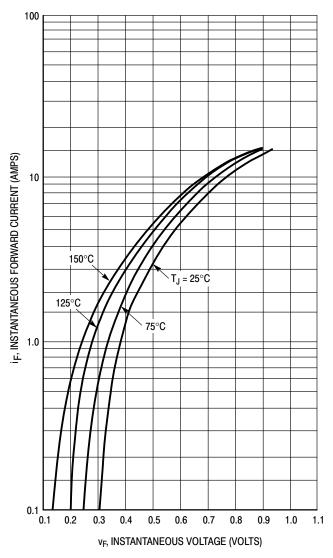
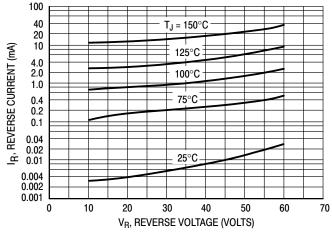


Figure 1. Typical Forward Voltage



*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these curves if V_R is sufficient below rated V_R .

Figure 2. Typical Reverse Current

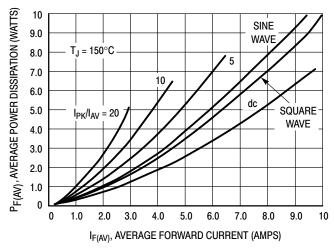


Figure 3. Average Power Dissipation

TYPICAL CHARACTERISTICS

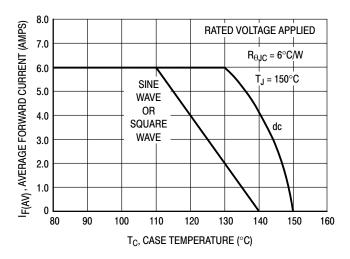


Figure 4. Current Derating, Case

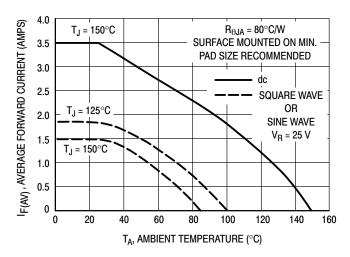


Figure 5. Current Derating, Ambient

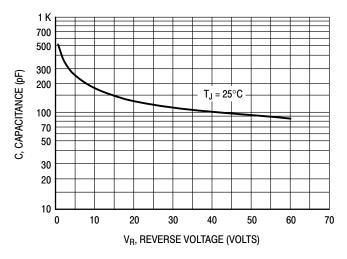
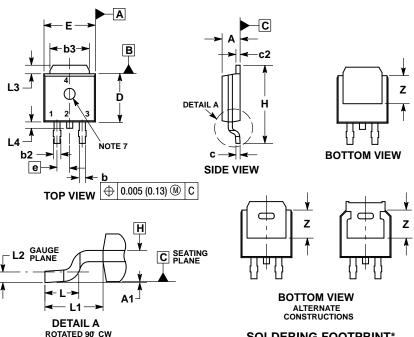


Figure 6. Typical Capacitance

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE F

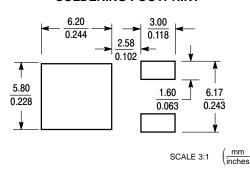


- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCHES
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.

 6. DATUMS A AND B ARE DETERMINED AT DATUM
- 7. OPTIONAL MOLD FEATURE.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.028	0.045	0.72	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.114	REF	2.90 REF		
L2	0.020	BSC	0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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